

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
7 December 2000 (07.12.2000)

PCT

(10) International Publication Number
WO 00/74131 A1

(51) International Patent Classification⁷: **H01L 21/48**,
21/50, 23/48, 23/28

Singapore 090110 (SG). **STRACK, Helmut** [AT/DE];
Speyererstrasse 6, D-80804 München (DE).

(21) International Application Number: PCT/SG99/00050

(74) Agent: **MCCALLUM, Graeme, David**; Lloyd Wise, Tanjong Pagar, P.O. Box 636, Singapore 910816 (SG).

(22) International Filing Date: 31 May 1999 (31.05.1999)

(81) Designated States (*national*): JP, KR, US.

(25) Filing Language: English

(84) Designated States (*regional*): European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).

(26) Publication Language: English

(71) Applicant (*for all designated States except US*):
SIEMENS AKTIENGESELLSCHAFT [DE/DE];
Wittelsbacherplatz 2, D-80333 München (DE).

Published:

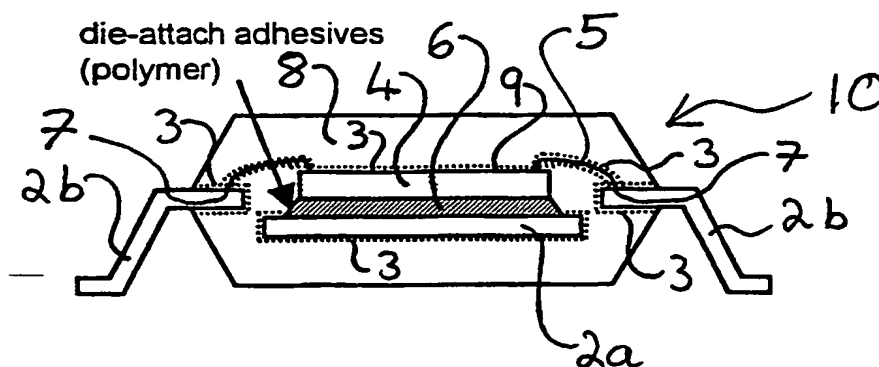
— With international search report.

(72) Inventors; and

(75) Inventors/Applicants (*for US only*): **LEE, Charles**
[SG/SG]; Apt. Blk 110, Bukit Purmei Road #03-152,

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: A METHOD OF ASSEMBLING A SEMICONDUCTOR DEVICE PACKAGE



(57) Abstract: A method of assembling a semiconductor device package (10) includes first attaching a semiconductor device (4) to a die-pad area (2a) of a leadframe (2). Electrical connections (5) are then formed between electrical contact areas on the semiconductor device (4) and electrical contact areas (7) on the leadframe (2) to form a device/leadframe assembly (2, 4, 5). An adhesion enhancing coating (3) is then deposited on exposed surfaces of the device/leadframe assembly (2, 4, 5) before encapsulating the coated device/leadframe assembly (2, 4, 5) in an electrically insulating material.

WO 00/74131 A1